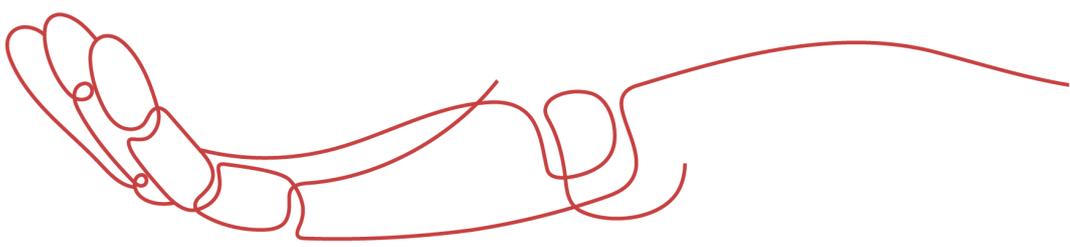


PRODUCT DATA SHEET



To learn more about JGSEMI, please visit our website at



Datasheet



Resources



Samples

Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO_questions@jgsemi.com.

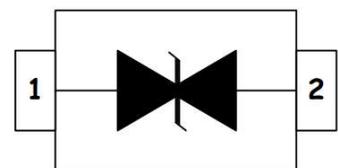
Features

- Ultra low leakage: nA level
- Operating voltage: 36V
- Low clamping voltage
- Complies with following standards:
 - IEC 61000-4-2 (ESD) immunity test
 - Air discharge: $\pm 30\text{kV}$
 - Contact discharge: $\pm 30\text{kV}$
 - IEC61000-4-4 (EFT) 40A (5/50ns)
 - IEC61000-4-5 (Lightning) 5A (8/20 μs)
- RoHS Compliant


SOD-323

Applications

- Cell Phone Handsets and Accessories
- Microprocessor based equipment
- Personal Digital Assistants(PDA's)
- Notebooks, Desktops, and Servers
- Portable Instrumentation
- Networking and Telecom
- Serial and Parallel Ports
- Peripherals



Mechanical Characteristics

- Package: SOD-323
- Lead Finish: Lead Free
- UL Flammability Classification Rating 94V-0
- Quantity Per Reel:3,000pcs
- Reel Size:7 inch

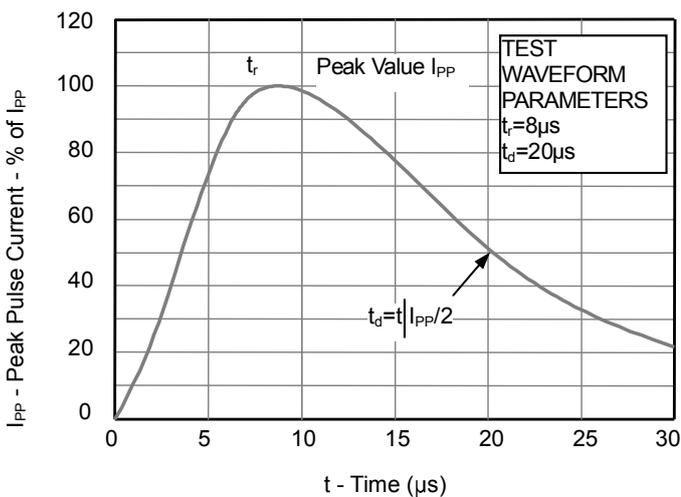
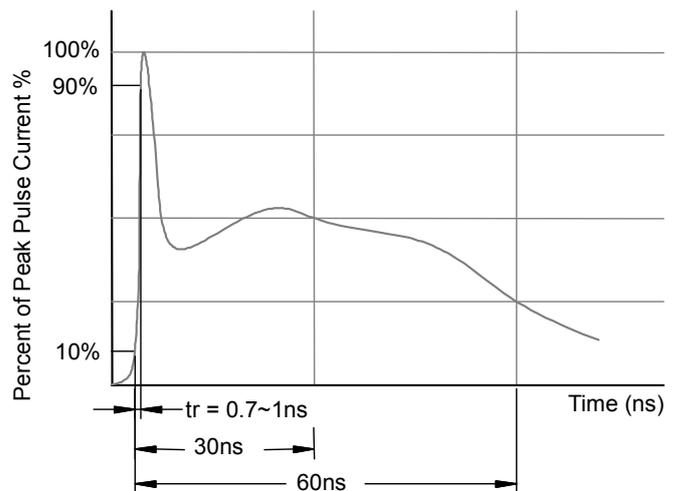
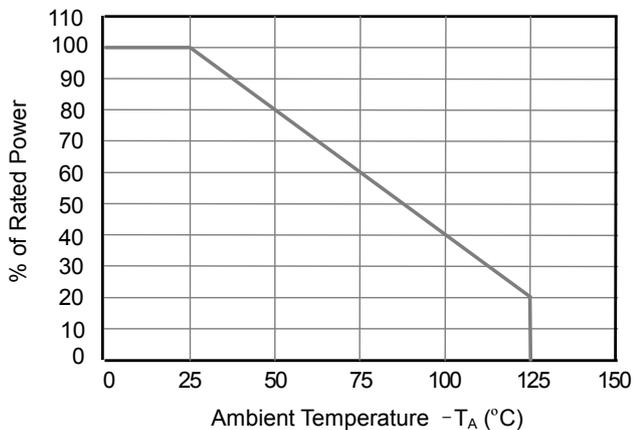
Absolute Maximum Ratings

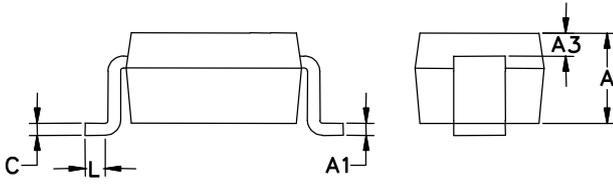
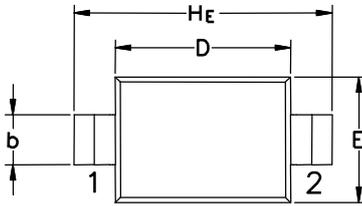
 (T_{amb}=25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20 μs)	P _{pp}	350	W
ESD per IEC 61000-4-2 (Air)	V _{ESD}	± 30	Kv
ESD per IEC 61000-4-2 (Contact)		± 30	
Operating Temperature Range	T _J	-55 to +125	°C
Storage Temperature Range	T _{STJ}	-55 to +150	°C

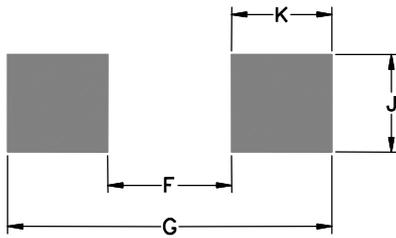
Electrical Characteristics (TA=25°C unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Reverse Working Voltage	V_{RWM}				36	V
Breakdown Voltage	V_{BR}	$I_T = 1mA$	40			V
Reverse Leakage Current	I_R	$V_{RWM} = 36V$			1	μA
Clamping Voltage	V_C	$I_{PP} = 1A$ (8 x 20 μs pulse)			60	V
Clamping Voltage	V_C	$I_{PP} = 5A$ (8 x 20 μs pulse)			75	V
Junction Capacitance	C_J	$V_R = 0V, f = 1MHz$		35		pF

Characteristic Curves
Fig1. 8/20 μs Pulse Waveform

Fig2. ESD Pulse Waveform (according to IEC 61000-4-2)

Fig3. Power Derating Curve


SOD-323 Package Outline & Dimensions


Symbol	Millimeters			Inches		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	0.80	0.90	1.00	0.031	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A3	0.15 REF			0.006 REF		
b	0.25	0.32	0.40	0.010	0.012	0.016
C	0.089	0.12	0.177	0.003	0.005	0.007
D	1.60	1.70	1.80	0.062	0.066	0.070
E	1.15	1.25	1.35	0.045	0.049	0.053
L	0.08			0.003		
H_E	2.30	2.50	2.70	0.090	0.098	0.105

Soldering Footprint


Symbol	Millimeters	Inches
F	1.60	0.063
G	2.85	0.112
J	0.83	0.033
K	0.63	0.025

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